PCN Number:		20230306001.1			PCN Date:		March 08, 2023		
Title: Datasheet for OPAx277									
Customer Contact: PCN Man			lanager	anager			Dep	ot:	Quality Services
Proposed 1 st Ship Date: June			8, 2	.023					
Change Type:									
Assembly Site				Design			Wafer	Bump Site	
Assembly Process			Χ	Data Sheet			Wafer	Bump Material	
Assembly Materials				Part number change			Wafer	Bump Process	
Mechanical Specification				Test Site			Wafer	Fab Site	
Packing/Shipping/Labeling				Test Process			Wafer	Fab Materials	
								Wafer	Fab Process
Notification Details									
Description of Change:									
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below.									
TEXAS INSTRUMENTS SBOS079C – MARCH 1999 – REVISED FEBRUARY 2023									

Changes from Revision B (April 2015) to Revision C (February 2023)	Page
 Updated the numbering format for tables, figures, and cross-references throughout the document 	1
Changed Applications bullets to include links	1
· Deleted text regarding identical specification for the single, dual, and quad versions	1
Changed Offset Trim pin type from "Input" to "—"	3
Changed "DFN" to "DRM (VSON)" in OPA2277 Pin Functions table	3
 Added table note for 10-mA current limit on input pins in Absolute Maxiimum Ratings 	6
Deleted operating temperature from Absolute Maximum Ratings	6
Deleted lead temperature from Absolute Maximum Ratings	6
Changed Thermal Information values for OPA2277 and OPA4277 SOIC packages	7
Added test conditions to Electrical Characteristics header	
Changed format of Electrical Characteristcs for readability	8
 Changed input offset voltage vs. time to long-term drift in Electrical Characteristics 	8
 Changed input bias current test condition to separate over temperature specification 	8
Deleted redundant row in open-loop gain parameter	8
Changed C _{LOAD} to C _L for consistency	8
 Changed Figure 6-14, Change in Input Bias Current vs Common-Mode Voltage, to correct typo in no 	
Changed "DFN package" to "DRM package (8-pin VSON)"	21
Changed "DFN package" to "DRM Package" and added "8-Pin VSON"	21
Changed Development Support section to show updated links and resources	

The datasheet number will be changing.

Device Family	Change From:	Change To:	
OPAx277	SBOS079B	SBOS079C	

These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/OPA2277

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Electrical specification performance changes as indicated above.

Changes to product identification resulting from this PCN:

None.

Product Affected:

Product Affected:			
OPA2277AIDRMT	OPA2277UA/2K5	OPA277PA	OPA277UAG4
OPA2277AIDRMTG4	OPA2277UA/2K5E4	OPA277PAG4	OPA277UG4
OPA2277P	OPA2277UAE4	OPA277U	OPA4277PA
OPA2277PA	OPA2277UAG4	OPA277U/2K5	OPA4277UA
OPA2277PAG4	OPA2277UG4	OPA277U/2K5G4	OPA4277UA/2K5
OPA2277U	OPA277AIDRMR	OPA277UA	OPA4277UA/2K5E4
OPA2277U/2K5	OPA277AIDRMT	OPA277UA/2K5	OPA4277UAE4
OPA2277U/2K5G4	OPA277AIDRMTG4	OPA277UA/2K5E4	OPA4277UAG4
OPA2277UA	OPA277P	OPA277UAE4	

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	<u>PCN ww admin team@list.ti.com</u>

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale

(<u>www.ti.com/legal/termsofsale.html</u>) or other applicable terms available either on <u>ti.com</u> or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.